



SOT1746-1

HSOP32, plastic, thermal enhanced small outline package; 32 terminals; 0.65 mm pitch; 7.5 mm x 11 mm x 2.22 mm body

1 October 2018

Package information

1 Package summary

Terminal position code	D (double)
Package type descriptive code	HSOP32
Package style descriptive code	HSOP (heatsink small outline package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	01-02-2016
Manufacturer package code	98ARL10543D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	11	-	mm
package width	-	7.5	-	mm
package height	-	2.22	-	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	32	-	



2 Package outline

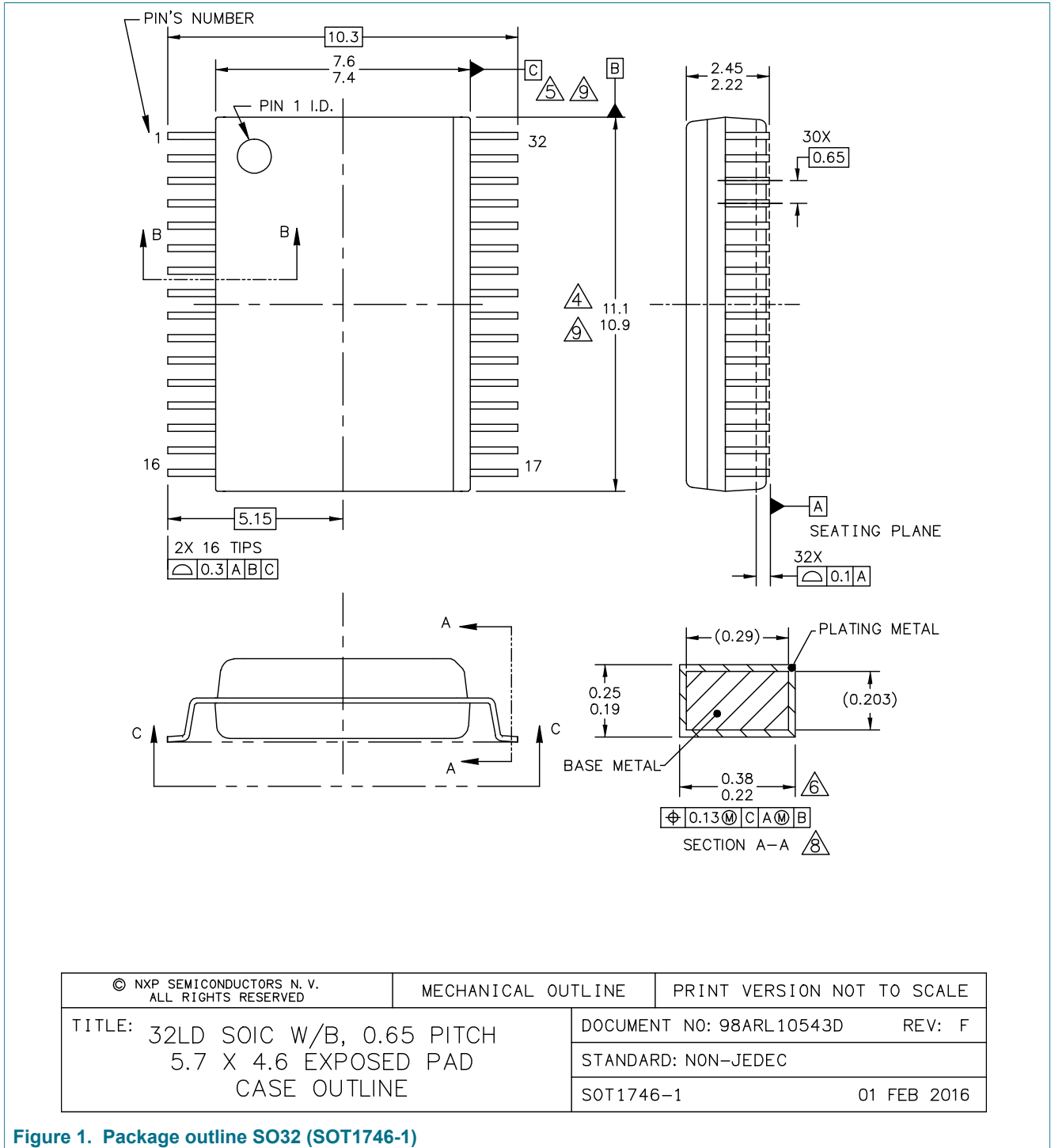


Figure 1. Package outline SO32 (SOT1746-1)

HSOP32, plastic, thermal enhanced small outline package; 32 terminals; 0.65 mm pitch; 7.5 mm x 11 mm x 2.22 mm body

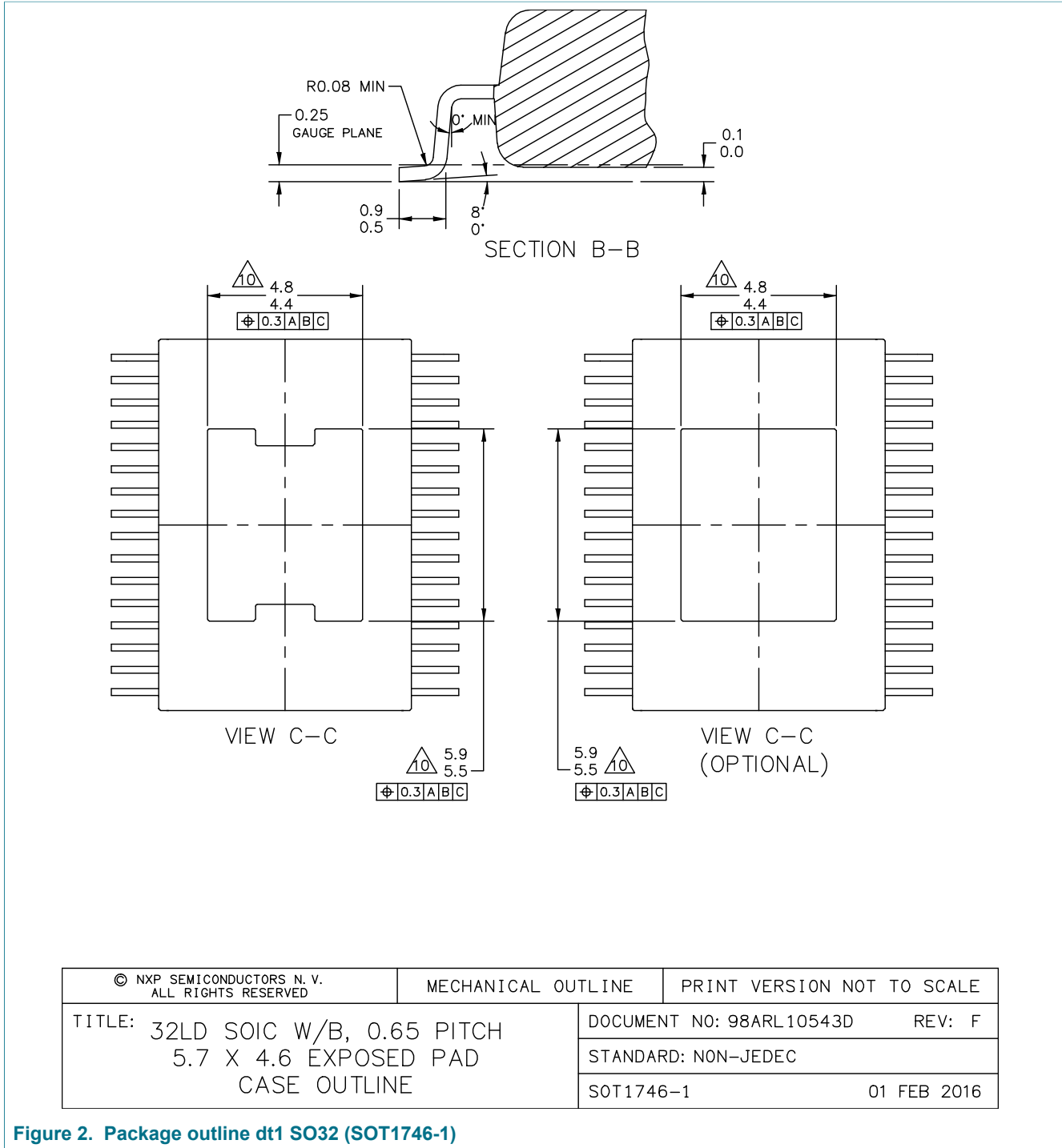


Figure 2. Package outline dt1 SO32 (SOT1746-1)

HSOP32, plastic, thermal enhanced small outline package; 32 terminals; 0.65 mm pitch; 7.5 mm x 11 mm x 2.22 mm body

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. DATUMS B AND C TO BE DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
4. THIS DIMENSION DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS. MOLD FLASH, PROTRUSION OR GATE BURRS SHALL NOT EXCEED 0.15 MM PER SIDE. THIS DIMENSION IS DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
5. THIS DIMENSION DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSIONS. INTER-LEAD FLASH AND PROTRUSIONS SHALL NOT EXCEED 0.25 MM PER SIDE. THIS DIMENSION IS DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
6. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.4 mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT LESS THAN 0.07 mm.
7. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
8. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 mm AND 0.3 mm FROM THE LEAD TIP.
9. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM. THIS DIMENSION IS DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTER-LEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
10. THESE DIMENSIONS RANGES DEFINE THE PRIMARY KEEP-OUT AREA. MOLD LOCKING AND RESIN BLEED CONTROL FEATURES MAY BE VISIBLE AND THEY MAY EXTEND TO 0.9mm FROM MAXIMUM EXPOSED PAD SIZE

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TITLE: 32LD SOIC W/B, 0.65 PITCH 5.7 X 4.6 EXPOSED PAD CASE OUTLINE	DOCUMENT NO: 98ARL10543D	REV: F
	STANDARD: NON-JEDEC	
	SOT1746-1	01 FEB 2016

Figure 3. Package outline note SO32 (SOT1746-1)

3 Legal information

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